

	1	2	3	4	5	6																																																																																																		
A	<div>PCB: FABRICATE TO IPC 6012 CLASS 2 VENDOR MARKINGS ON BOTTOM SIDE ONLY! VENDOR MARKINGS IN SILKSCREEN ONLY!</div> <div>FIDUCIAL MARKS: FID1, FID2, FID3</div> <div>DESIGNED BY: ENG. ANDRÉ A. M. ARAÚJO</div>					A																																																																																																		
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BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1.5888 mm
Board overall dimensions:	100.0000 mm x 82.0000 mm		
Min track/spacing:	0.1270 mm / 0.1270 mm	Min hole diameter:	0.3000 mm
Copper Finish:	HAL SnPb	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		

Eng. André A. M. Araújo		
Mechatronics Lab		
Sheet:		
File: EMBARCADOS – CURSO PCB.kicad_pcb		
Title: EMBARCADOS – CURSO PCB		
Size: A4	Date: 2024–11–16	Rev: 00
KiCad E.D.A. 8.0.6		Id: 1/1